Takatori

MODEL

DAM-812M

Semi-Automatic Die-Attach Mounter

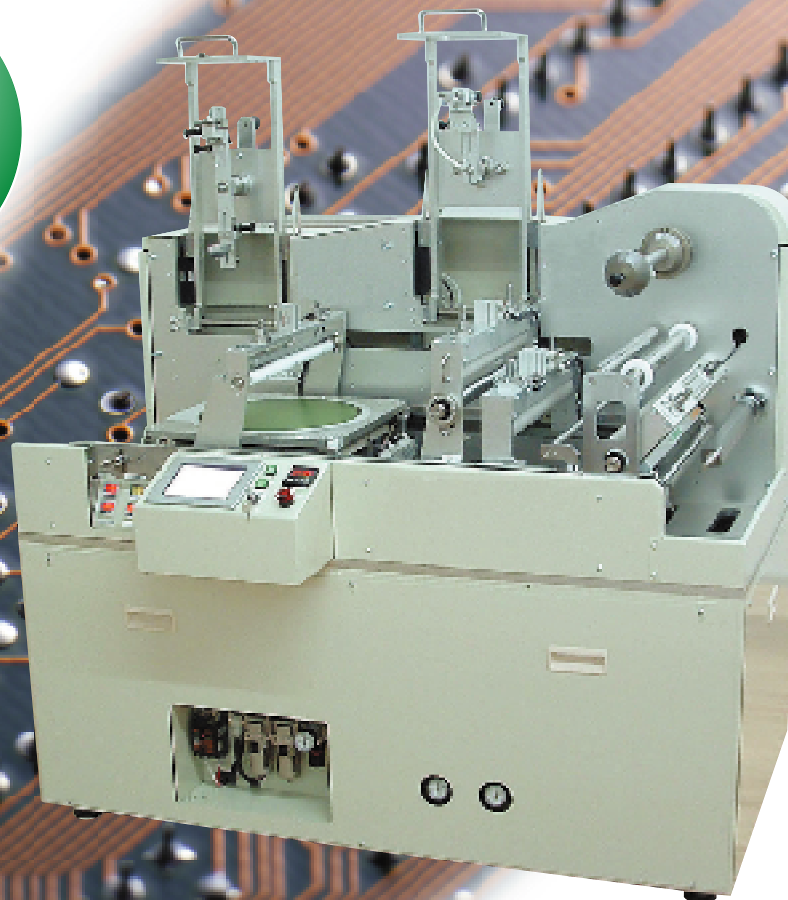
Outline

This is semi-automatic machine for Dicing-Die bonding film (2 layers) for 8-12 inch wafer. And applicable for smaller wafer.

Features

- ●Applicable for Dicing-Die bonding film (2 layers) and conventional die attach film (Single layer) by changing jig.
- ●Applicable for ultra thin wafers less than 50microns with Wafer Support System.
- ●Laminating speed control, pressure control ensures stable lamination.

8・12inch Wafers



Specification		DM-812M
Wafer Size		8 inch、12 inch
Tape Width		Dicing die-bonding film / 8inch :W 300mm 、12inch :W 400mm Die-attach film / 8inch :W 240mm 、12inch :W 350mm
Utilities	Power	AC200V　Single phase 50／60Hz　2KVA
	Air	Pressure 0.5Mpa
	Vacuum sourse	—50Kpa
Dimensions		D 910 × W 1,350 × H 1,250mm
Weight		150 kg

System appearance and specifications are subject to change without prior notice from the supplier.

313-1 Shindo-cho, Kashihara City, Nara, Japan 634-8580
Phone: +81(0)744-24-7670
Fax: +81(0)744-24-8352
URL http://www.takatori-g.co.jp E-mail info@takatori-g.co.jp

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